# CLAIMS

[Claim 1]

A maleimide resin composition comprising

(A) one or more selected from a group consisting of a maleimide compound having one or more N-substituted maleimide groups and a derivative thereof, and

(B) a polymer having a hydrocarbon chain or a polyether chain in a main chain thereof, wherein

the component (A) dissolves in an alcohol-based solvent, a ketone-based solvent, an aromatic hydrocarbon-based solvent, an ester-based solvent, or a nitrogen atom-containing solvent in an amount of 30% by mass or more at 25°C,

wherein the component (B) comprises (B1) a modified conjugated diene polymer obtained by modifying (b1) a conjugated diene polymer having a vinyl group in a side chain thereof with (b2) a maleimide compound having two or more N-substituted maleimide groups.

[Claim 2]

The maleimide resin composition according to claim 1, wherein the component (A) is a maleimide compound containing an alicyclic hydrocarbon group.

[Claim 3]

The maleimide resin composition according to claim 2, wherein the alicyclic hydrocarbon group is contained as part of an indane ring.

[Claim 4]

The maleimide resin composition according to any one of claims 1 to 3, wherein the component (B1) has, on a side chain thereof, a substituent obtained by reacting the vinyl group of the component (b1) with the N-substituted maleimide group of the component (b2).

[Claim 5]

The maleimide resin composition according to any one of claims 1 to 4, wherein the component (b1) is polybutadiene having a 1,2-vinyl group.

[Claim 6]

The maleimide resin composition according to any one of claims 1 to 5, wherein a content ratio of the component (A) and the component (B) [(A)/(B)] is 0.3 to 3.0 on a mass basis.

[Claim 7]

A prepreg comprising the maleimide resin composition according to any one of claims 1

to 6 or a semi-cured product of the maleimide resin composition.

[Claim 8]

A laminate comprising a cured product of the maleimide resin composition according to any one of claims 1 to 6 or a cured product of the prepreg according to claim 7, and a metal foil.

[Claim 9]

A resin film comprising the maleimide resin composition according to any one of claims 1 to 6 or a semi-cured product of the maleimide resin composition.

[Claim 10]

A printed wiring board comprising one or more selected from a group consisting of a cured product of the maleimide resin composition according to any one of claims 1 to 6, a cured product of the prepreg according to claim 7, and the laminate according to claim 8.

[Claim 11]

A semiconductor package comprising the printed wiring board according to claim 10 and a semiconductor element.